

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
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Property Type	Number
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ASSIGNMENT

WHEREAS Zhu, Hailong, (hereinafter referred to as Assignor), have made an invention entitled: SEMICONDUCTOR DEVICE AND METHOD FOR FORMING THE SAME for which I am the listed inventor for the application for United States Letters Patent referred to below as the Formal Application.

WHEREAS INSTITUTE OF MICROELECTRONICS, CHINESE ACADEMY OF SCIENCES whose mailing address is No. 3 Beitucheng West Road, Chaoyang District, Beijing 100079, P. R. China (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the above-identified Formal Application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee is hereby acknowledged, I, as Assignor, have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, MY entire right, title, and interest in and to this invention, the above-identified patent application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, and all rights to claim priority on the basis of such applications, and all applications for Letters Patents which may hereafter be filed for this invention in any foreign country and all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof, and WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent of this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I HEREBY covenant that I have the full right to convey the interest assigned by this Assignment, and I have not executed and will not execute any agreement in conflict with this Assignment;

AND, I HEREBY further covenant and agree that I will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to ME respecting this invention, and testify in any legal proceedings; sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuing, and reissue applications, make all lawful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent prosecution for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns;

AND, I HEREBY further covenant and agree that I will assign, and hereby do assign, to Assignee, its lawful successors and assigns, MY entire right, title, and interest in and to any and all patent applications, both United States and foreign, and all Letters Patent that may be granted thereon, that claim priority to this invention or to the above-identified provisional or non-provisional applications in any manner, such applications specifically including, but not limited to, divisionals, continuations, continuations-in-part, and all other provisional and non-provisional applications.

Assignor: Zhu, Hailong
Address of Assignor:
93 Autumn Dr., Poughkeepsie
NY 12603, USA


Assignor's Signature

Date: 3/10/2011

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